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MOV





AON6360-MS

Product specification





Description

The AON6360-MS uses advanced trench technology to provide excellent RDS(ON), low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

Features

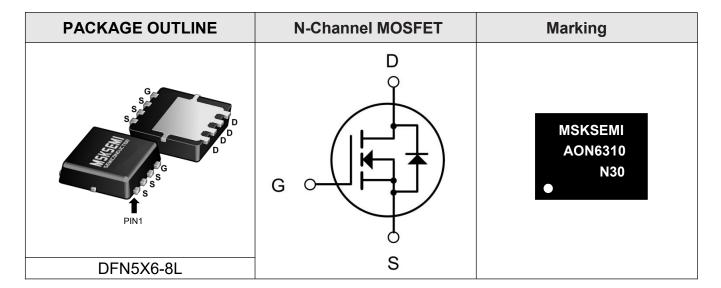
VDS = 30V ID =120A

 $RDS(ON) < 4.4m\Omega VGS=10V$

Application

- Battery protection
- Load switch
- Uninterruptible power supply

Reference News



Absolute Maximum Ratings (TC=25℃unless otherwise noted)

Symbol	Parameter	Rating	Units
V _D s	Drain-Source Voltage	30	V
Vgs	Gate-Source Voltage	±20	V
In@Tc=25°C	Continuous Drain Current, V _{GS} @ 10V ^{1,6}	120	А
Ib@Tc=100°C	Continuous Drain Current, V _{GS} @ 10V ^{1,6}	66	А
Ірм	Pulsed Drain Current ²	320	А
EAS	Single Pulse Avalanche Energy³	180	mJ
las	Avalanche Current	60	Α
P _D @ T _C =25 °C	Total Power Dissipation ⁴	187	W
Тѕтс	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C
Reja	Thermal Resistance Junction-Ambient ¹	62	°C/W
Rejc	Thermal Resistance Junction-Case ¹	1.1	°C/W



Electrical Characteristics (TJ=25 $^{\circ}$ C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	V _G s=0V , I _D =250uA	30			V
△BV _{DSS} /△T _J	BVpss Temperature Coefficient	Reference to 25°C , I _D =1mA		0.014		V/°C
		Vgs=10V , Ip=30A		3.5	4.4	
Rds(on)	Static Drain-Source On-Resistance ²	Vgs=4.5V , ID=15A		4.6	5.8	$m\Omega$
VGS(th)	Gate Threshold Voltage		1.2		2.5	V
${^\triangle V}_{GS(th)}$	V _{GS(th)} Temperature Coefficient	V _G s=V _D s , I _D =250uA		-4		mV/°C
		V _{DS} =24V , V _{GS} =0V , T _J =25°C			1	
IDSS	IDSS Drain-Source Leakage Current	V _{DS} =24V , V _{GS} =0V , T _J =55°C			5	uA
Igss	Gate-Source Leakage Current	V _G S= ±20V , V _D S=0V			±100	nA
gfs	Forward Transconductance	VDS=5V, ID=30A		50		S
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		1.7		Ω
Qg	Total Gate Charge (4.5V)			56.9		
Qgs	Gate-Source Charge	V _{DS} =15V , V _{GS} =10V , I _D =15A		13.8		nC
Qgd	Gate-Drain Charge			23.5		
Td(on)	Turn-On Delay Time			20.1		
Tr	Rise Time	V _{DD} =15V , V _{GS} =10V ,		6.3		
Td(off)	Turn-Off Delay Time	Rg=3.3 , Ip=1A		124.6		ns
Tf	Fall Time			15.8		
Ciss	Input Capacitance			4345		
Coss	Output Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz		340		рF
Crss	Reverse Transfer Capacitance			225		
ls	Continuous Source Current ^{1,6}	V _G =V _D =0V , Force Current			85	Α
VsD	Diode Forward Voltage ²	V _G s=0V , I _S =1A , T _J =25°C			1.2	V



Typical Electrical and Thermal Characteristics

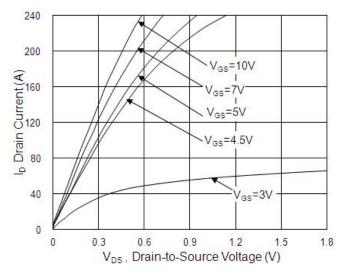
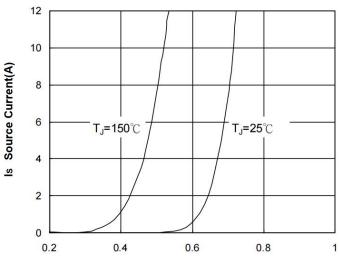


Fig.1 Typical Output Characteristics



V_{SD} , Source-to-Drain Voltage (V)

Fig. 3 Forward Characteristics of Reverse

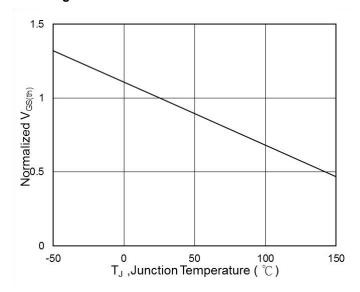


Fig.5NormalizedVgs(th)v.s TJ

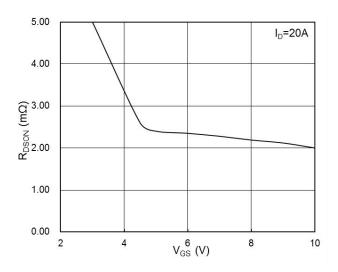


Fig.2 On-Resistance v.s Gate-Source

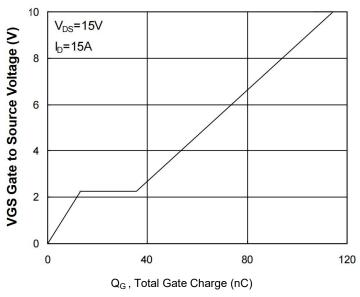


Fig. 4 Gate-Charge Characteristics

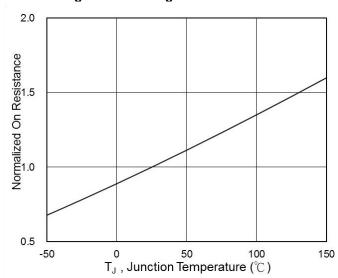
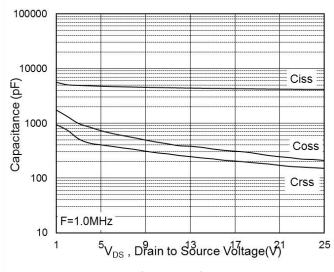


Fig.6Normalized RDSONV.S TJ





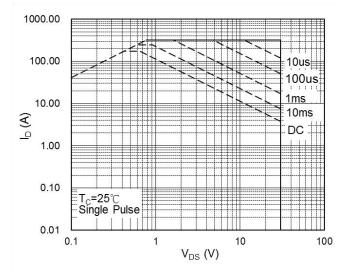
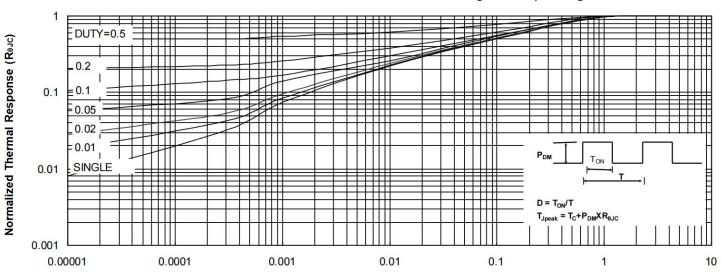


Fig.7 Capacitance

Fig.8Safe Operating Area



t, Pulse Width (s)

Fig. 9 Normalized Maximum Transient Thermal Impedance

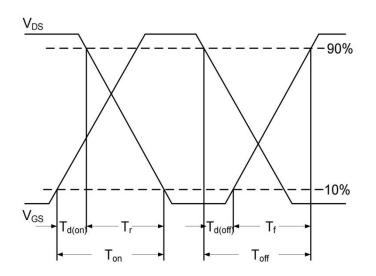
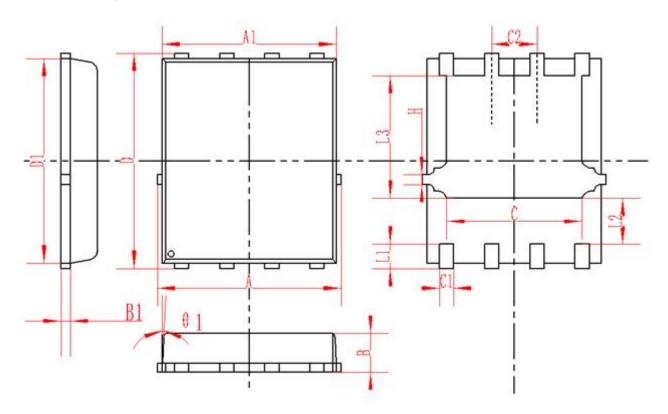


Fig.10 Switching Time Waveform

Fig.11 Unclamped Inductive Switching Waveform



DFN5X6-8L Package Information



CVN ADOL	MM		INCH			
SYMBOL	MIN	NOM	MAX	MIN	NOM	MAX
А	4.95	5	5.05	0.195	0.197	0.199
A1	4.82	4.9	4.98	0.190	0.193	0.196
D	5.98	6	6.02	0.235	0.236	0.237
D1	5.67	5.75	5.83	0.223	0.226	0.230
В	0.9	0.95	1	0.035	0.037	0.039
B1	0.254REF		0.010REF			
С	3.95	4	4.05	0.156	0.157	0.159
C1	0.35	0.4	0.45	0.014	0.016	0.018
C2	1.27TYP		0.5TYP			
θ1	8。	10 _°	12。	8。	10 _°	12。
L1	0.63	0.64	0.65	0.025	0.025	0.026
L2	1.2	1.3	1.4	0.047	0.051	0.055
L3	3.415	3.42	3.425	0.134	0.135	0.135
Н	0.24	0.25	0.26	0.009	0.010	0.010

REEL SPECIFICATION

P/N	PKG	QTY
AON6360-MS	DFN5X6-8L	5000



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DMN1017UCP3-7 EFC2J004NUZTDG P85W28HP2F-7071 DMN1053UCP4-7 NTE2384 DMC2700UDMQ-7 DMN2080UCB4-7
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STF5N65M6 IRF40H233XTMA1 STU5N65M6 DMN6022SSD-13 DMN13M9UCA6-7 DMTH10H4M6SPS-13 IPS60R360PFD7SAKMA1
DMN2990UFB-7B SSM3K35CT,L3F IPLK60R1K0PFD7ATMA1 2N7002W-G MCAC30N06Y-TP IPWS65R035CFD7AXKSA1
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